

SPECIFICATIONS

CUSTOMER: _____

DESCRIPTION: _____ Chip ant

CUSTOMER PART NO: _____

OUR MODEL NO: _____ **PBX1608MA02**

DATE: _____

PLEASE RETURN TO US ONE COPY OF “SPECIFICATION FOR APPROVAL”
WITH YOUR APPROVED SIGNATURES

UNLESS OTHER SPECIFIED TOLERANCES ON:

$X=\pm$ $X.X=\pm$ $X.XX=$
ANGLES $=\pm$ **HOLE DIA** $=\pm$

SCALE: N/A

UNIT: mm

DRAWN BY : Sera

CHECKED BY: XD

DESIGNED BY: Sera

APPROVED BY: XD



PENGBANKING

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TITLE: CHIP2450-1608 Specification

DOCUMENT
NO.

1608

SPEC REV.

P1

PBX1608MA02 Specification

Operating Temp. : -40℃~+85℃

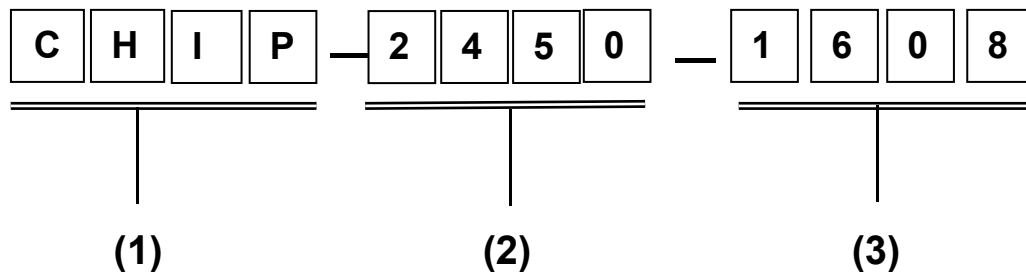
1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

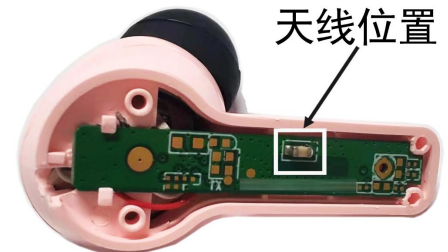
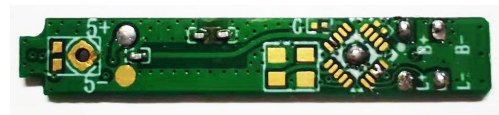
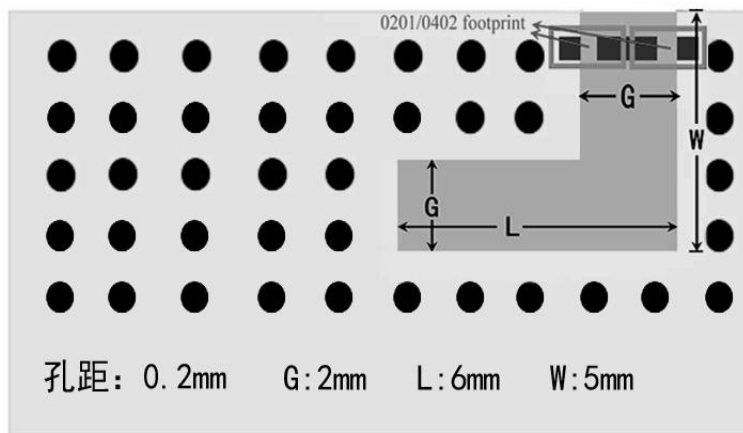
2. APPLICATIONS:

- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

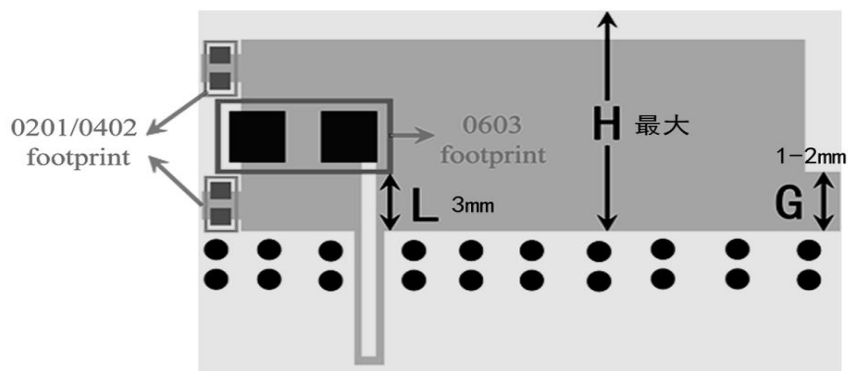
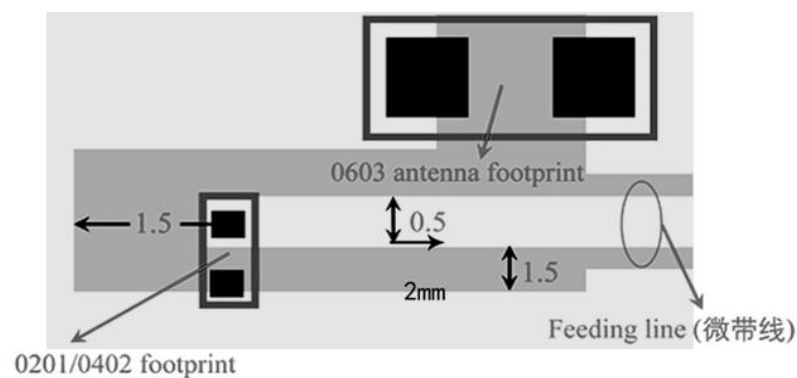
3. PRODUCT IDENTIFICATION



●: mm



天线需放置在PCBA外层



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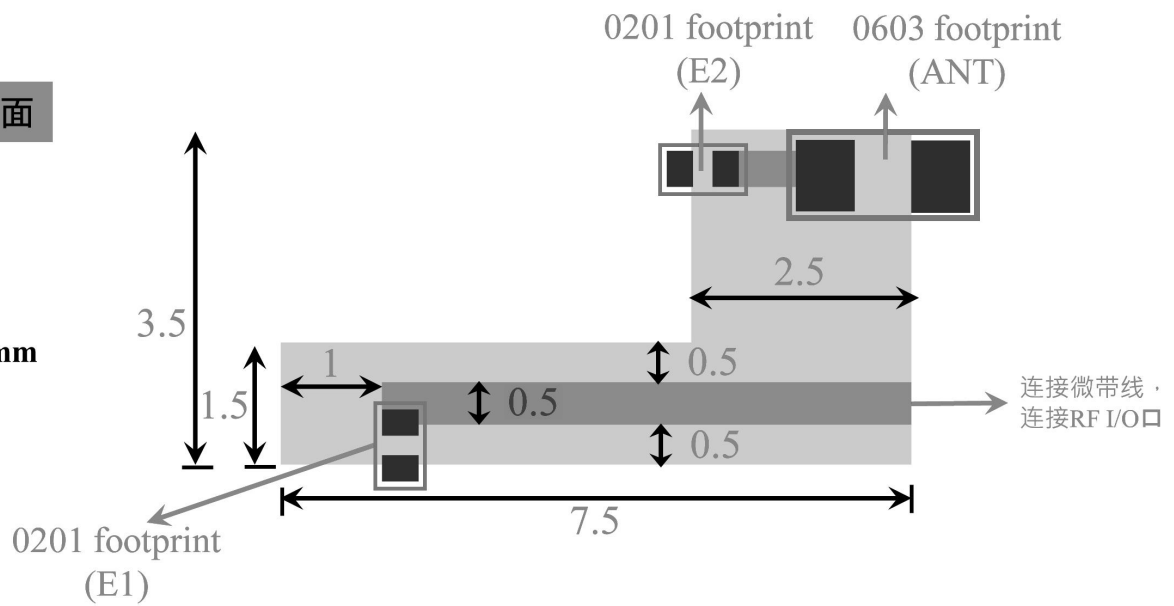
SPEC REV.

P1

(3.5mm×7.5mm)

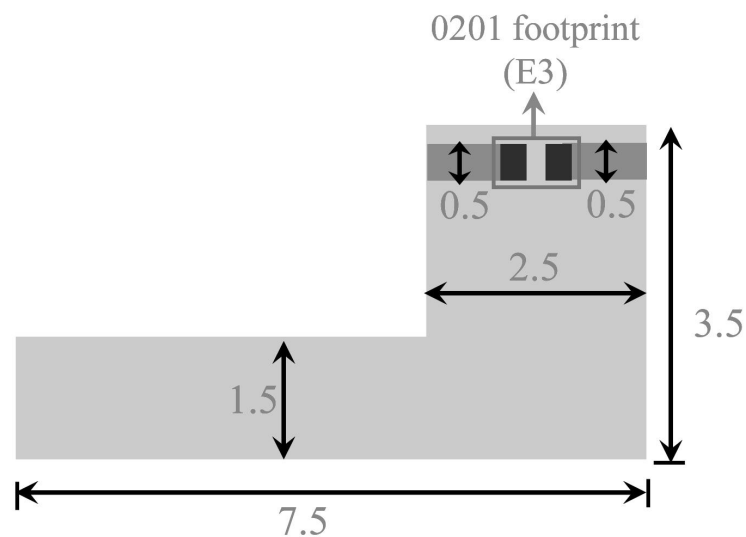
TOP面

Unit:mm

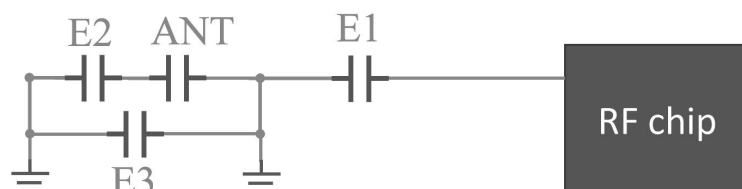


BOTTOM面

Unit:mm



原理图



UNLESS OTHER SPECIFIED TOLERANCES ON:

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ANGLES = ±

HOLE DIA = ±



PENG BAN XING

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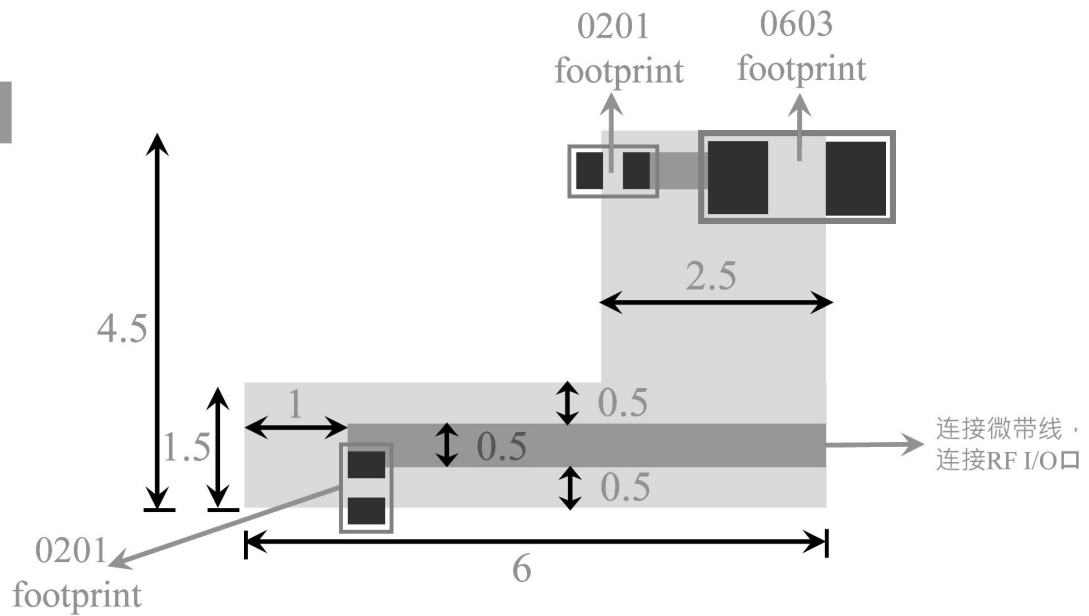
SPEC REV.

P1

(4.5mm×6mm)

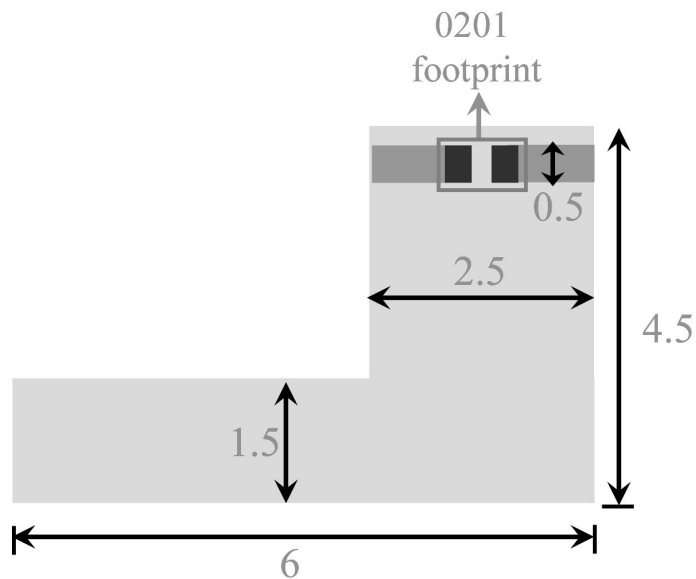
TOP面

Unit:mm



BOTTOM面

Unit:mm



UNLESS OTHER SPECIFIED TOLERANCES ON:

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ANGLES = ±

HOLE DIA = ±



PENG BANKING

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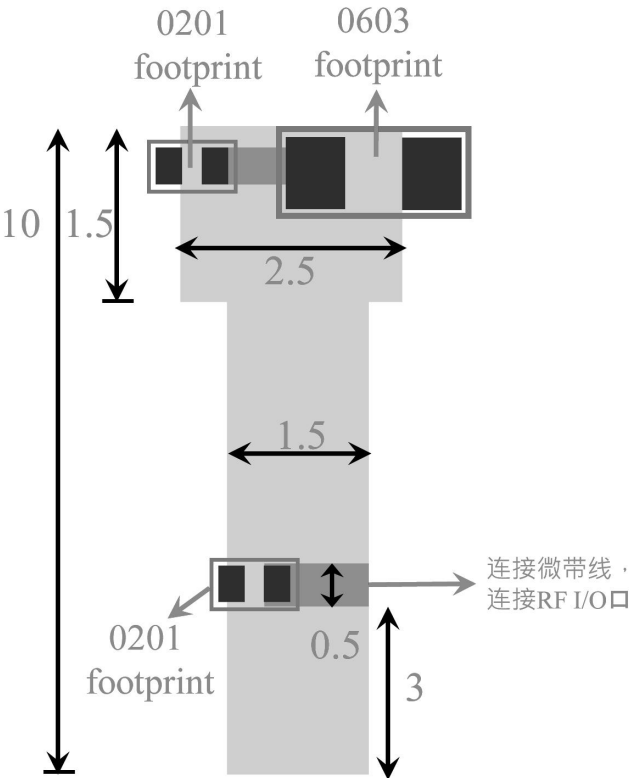
SPEC REV.

P1

(1.5mm×10mm)

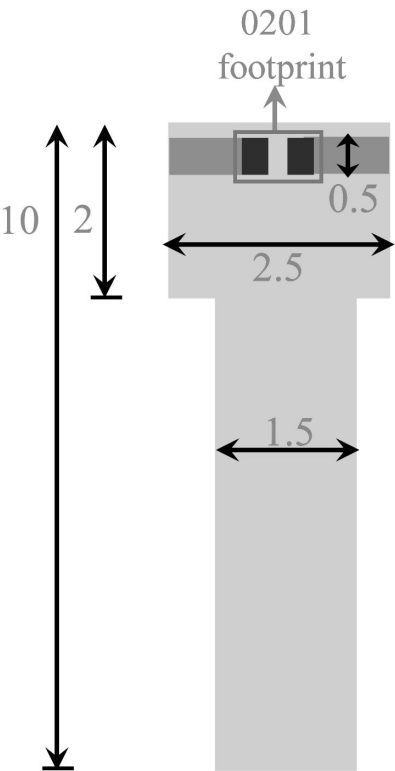
TOP面

Unit:mm



BOTTOM面

Unit:mm

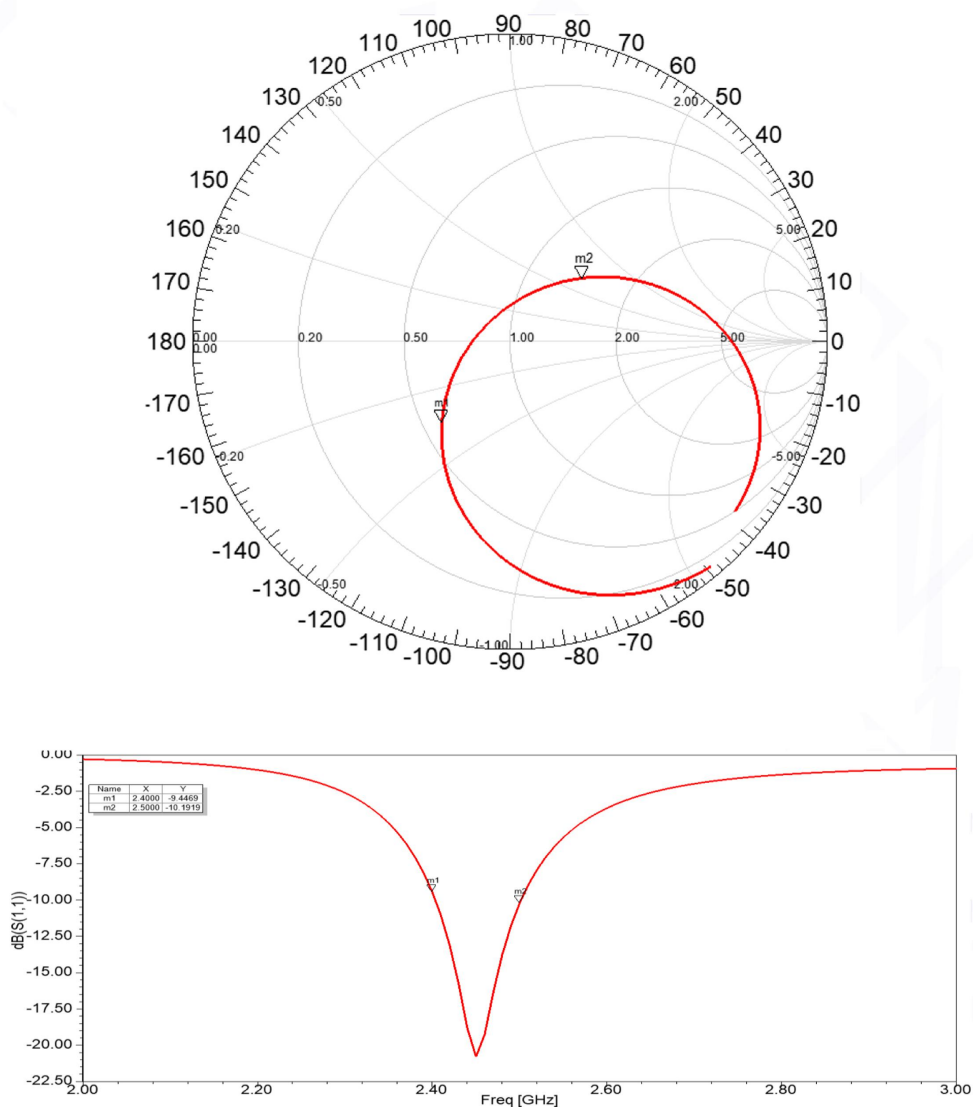


UNLESS OTHER SPECIFIED TOLERANCES ON: X=± X.X=± X.XX=± ANGLES = ± HOLEDIA = ±		 PENG BANKING	
SCALE: N/A	UNIT: mm	THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PBXY TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION	
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		1608	P1

Electrical Characteristics

	Feature	Specification
1	Central frequency	2.45GHz
2	Bandwidth	>150MHz
3	Peak gain	2.78 dBi
4	VSWR	<2
5	Polarization	Linear
6	Azimuth beamwidth	Omnidirectional
7	Impedance	50 Ω

Characteristic Curves



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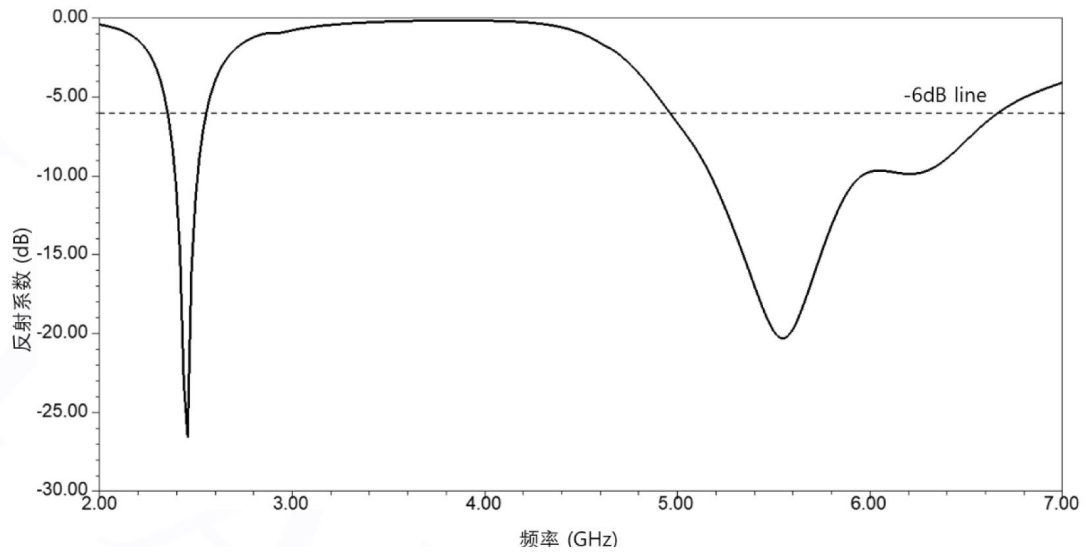
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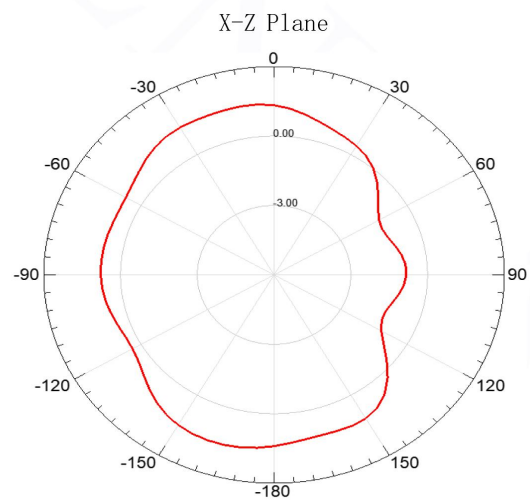
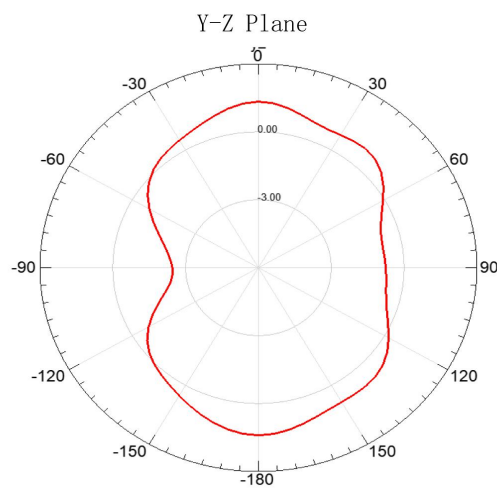
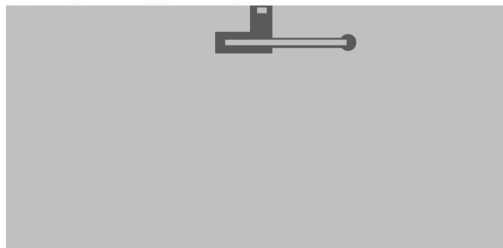
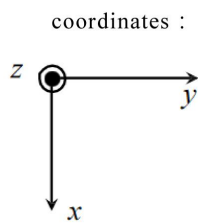
1608

SPEC REV.

P1



Radiation Pattern



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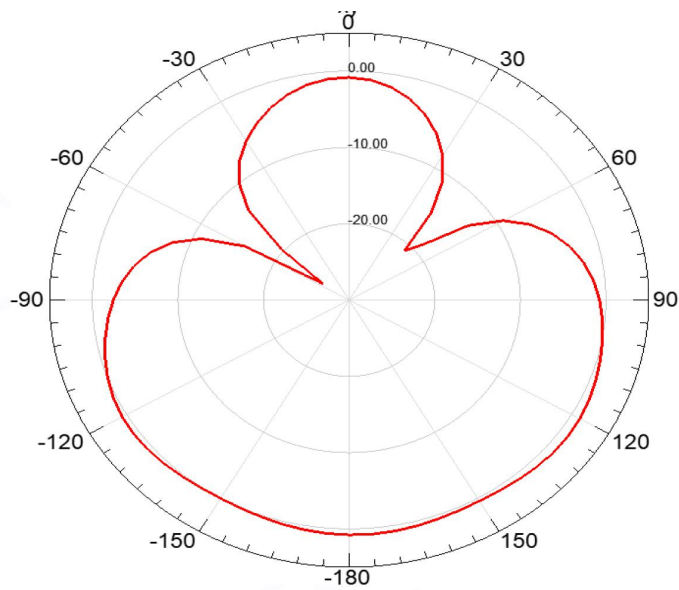
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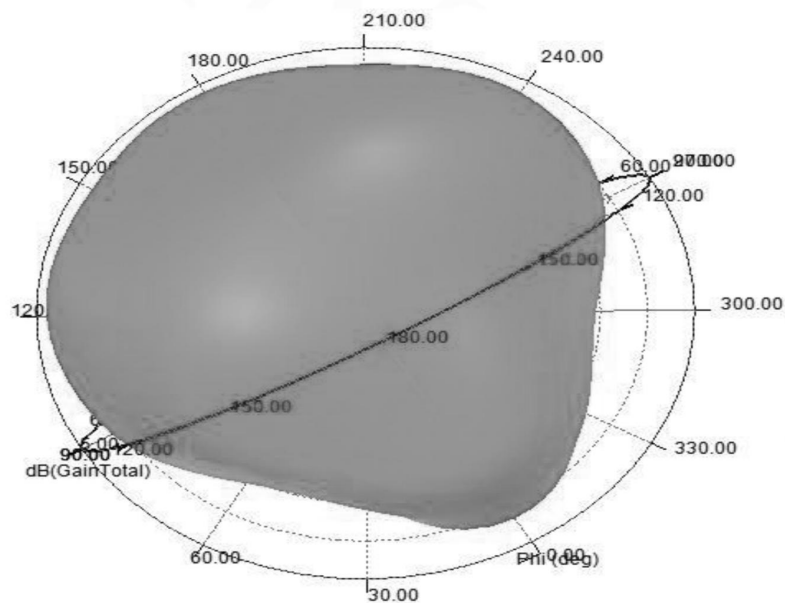
1608

SPEC REV.

P1



3D Radiation Pattern



Frequency	2400MHz	2450MHz	2500MHz
Avg. gain	-1.92	-1.35	-1.56
Peak gain	1.79	2.78	2.66
Efficiency	74.55	80.25	76.98

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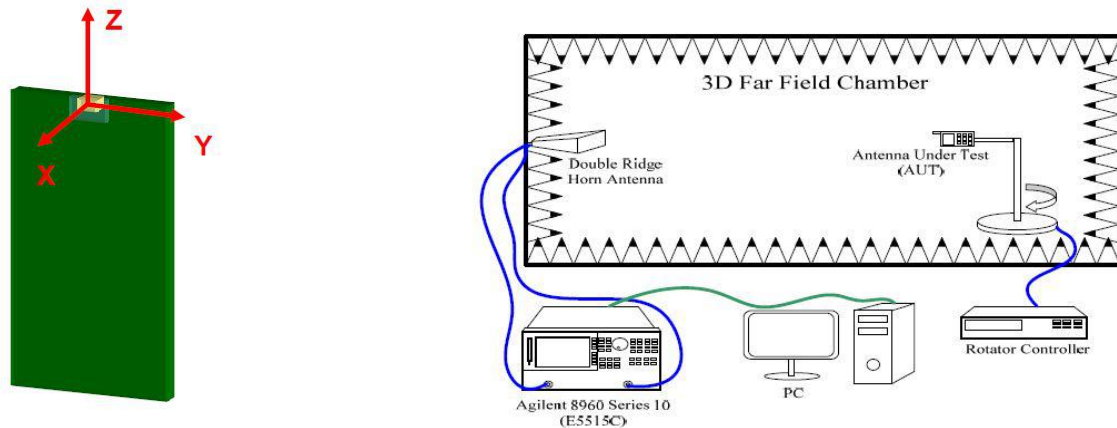
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P1

Radiation Pattern

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.



Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30±3 minutes at -40° C±5° C, 2. Convert to +105° C (5 minutes) 3. 30±3 minutes at +105° C±5° C, 4. Convert to -40° C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: 85±5° C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : 260±5°C 2. Bathing time: 10±1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of 245±5°C for 3±1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within 0 ~ 30°C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40°C to +105°C.

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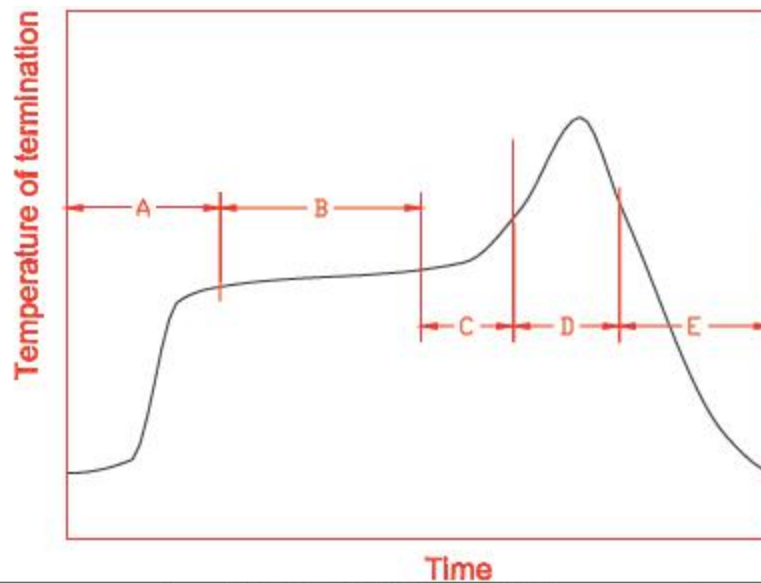
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8. Recommended Reflow Soldering



A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
B	Preheating	140°C to 160°C	60s to 120s
C	2 nd rising temperature	Preheating to 200°C	20s to 40s
D	Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
		if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s

*reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

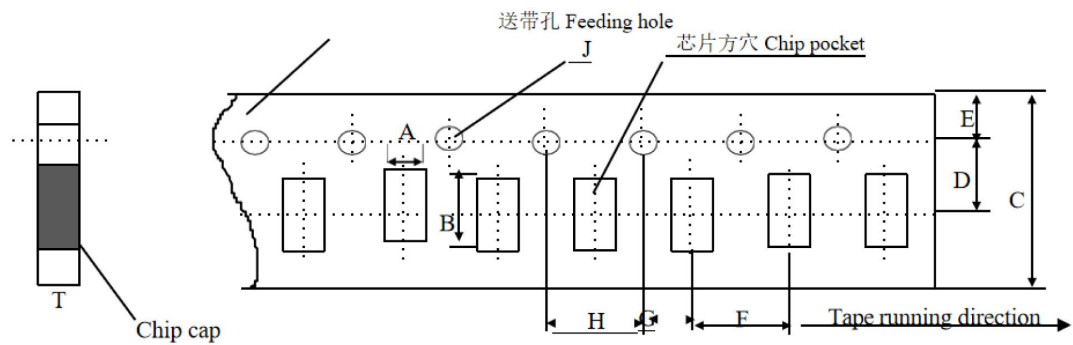
- (a) The tip temperature must be less than 350° C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

Note that excess of soldering volume will easily get crack the body of this product.

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Dimensions of paper taping:

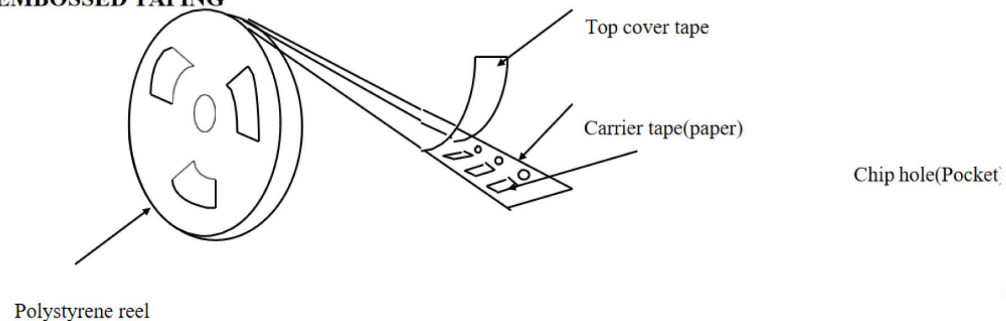


Unit: mm

代号 Code 纸带规格 papersize	A	B	C	D*	E	F	G*	H	J	T
尺寸	1.10 ±0.10	1.90 ±0.10	8.00 ±0.10	3.50 ±0.05	1.75 ±0.10	4.00 ±0.10	2.00 ±0.10	4.00 ±0.10	1.50 -0/+0.10	1.10 Max

Reel (4000 pcs/Reel)

EMBOSED TAPING



Storage Period

The guaranteed period for solderability is 6 months (Under deliver package condition).
Temperature: 5~40°C /Relative Humidity: 20~70%

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